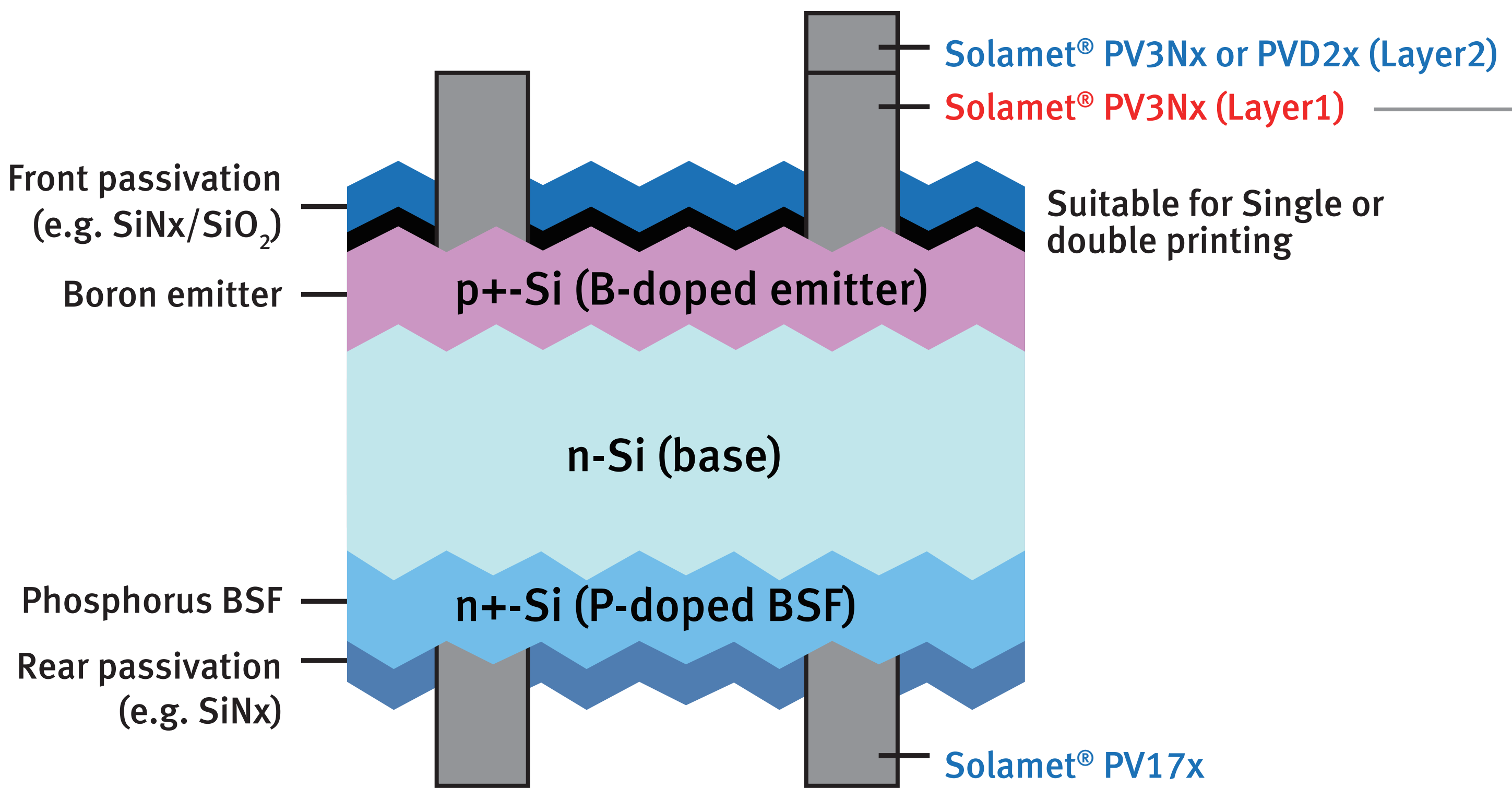
# EFFICIENCY
## PHOTOVOLTAIC METALLIZATIONS

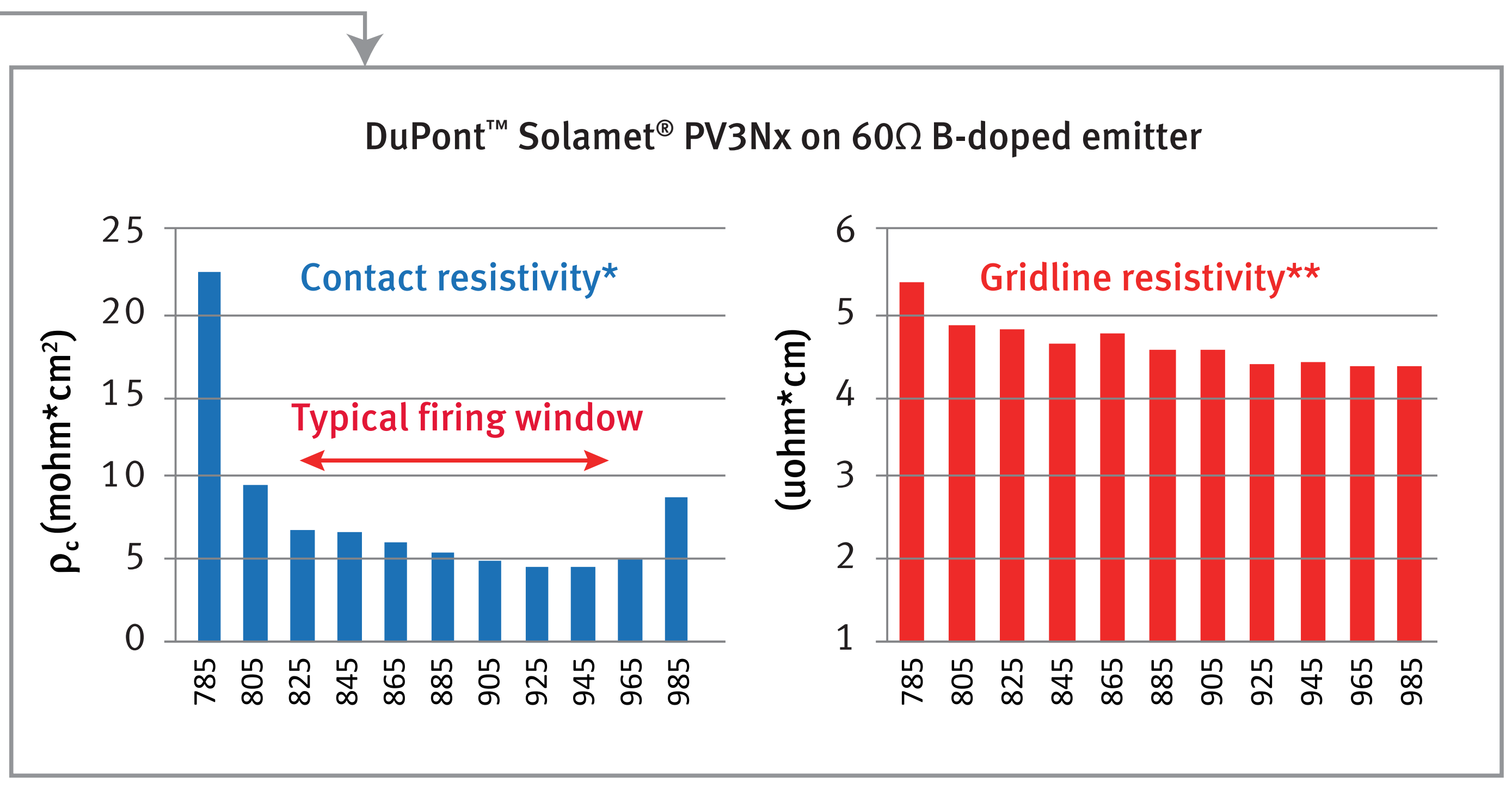
## On target to boost cell efficiency to 22% in 2015

### DuPont™ Solamet® PV3Nx silver/aluminum paste for p-type emitter

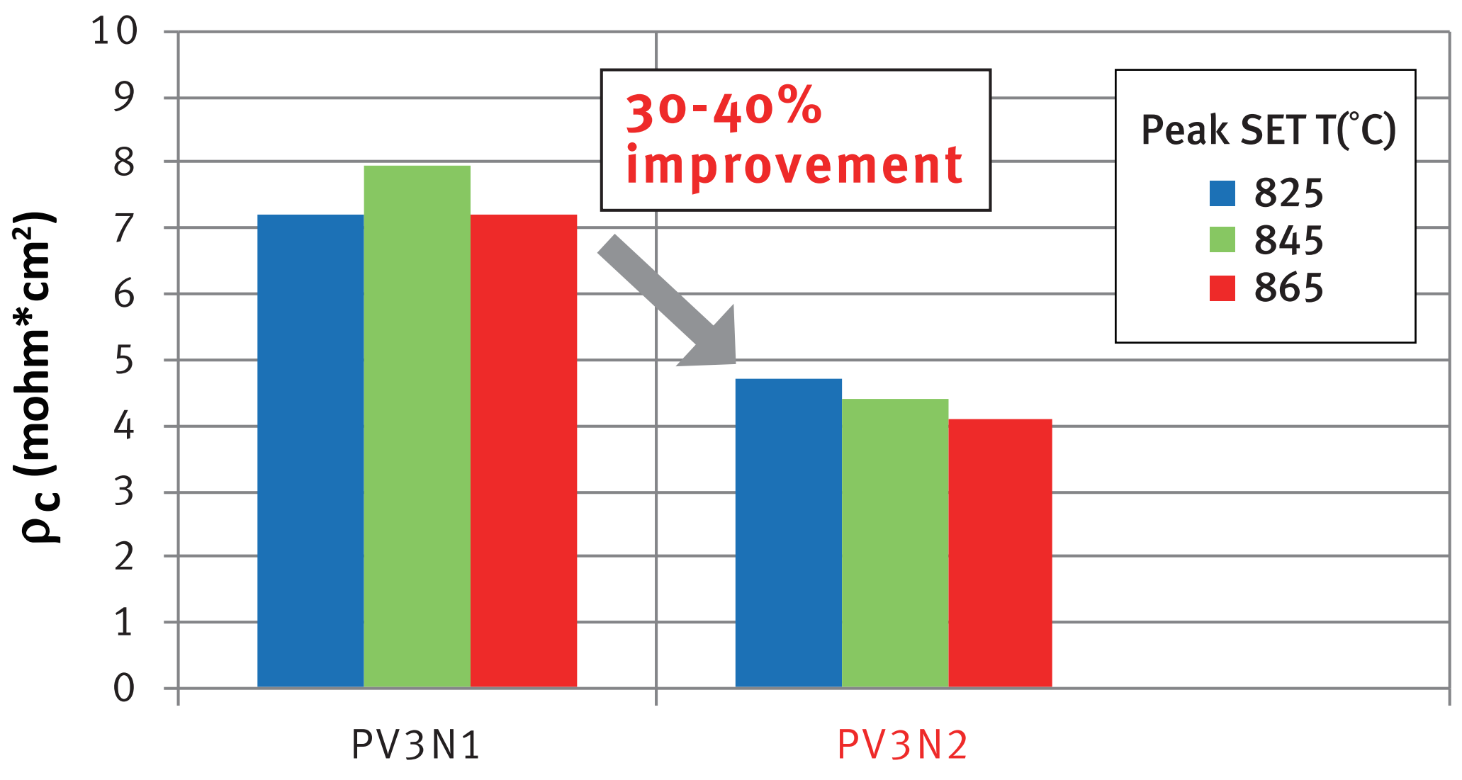
- Fineline printability (for gridlines with screen printing)
- Fire-through passivation layer
- Low contact resistivity on B-doped emitter layer
- Low gridline resistivity (high conductivity)
- Co-fireable with rear side contacts
- Good solderability and adhesion

### DuPont™ Solamet® complete metallization package for higher efficiency





### Contact resistivity on B-doped emitter*



- The new generation Solamet® PV3N2 provides 30-40% better contact resistivity on B-doped emitter compared to Solamet® PV3N1.

* Measured by TLM.

** $R_{gl}$ measured on fired-through contacts. Apparent values calculated assuming uniform line width and height. Crosssectional areas of fired gridlines measured using confocal microscope.